**REVIEW PAPER**



# **Design and Integration of Planar Inductances on PCB Application Passive Type Filters**

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#### **Abstract**

This paper is a synthesis of work encompassing simulation and experimental results aimed at designing, manufacturing and characterizing various fxed and variable width circular and square spiral inductance topologies deposited on a PCB-FR4 substrate. These inductors will compose flters for diferent applications of electronics and low power electronics. These prototypes of planar inductances were made at LAPLACE laboratory in Toulouse.

**Keywords** Planar inductor · Integration · Filter · PCB

# **1 Introduction**

Power electronics is currently evolving towards integration, as a result of the constraints related to the need to miniaturize but also to reduce manufacturing costs. In many cases, hybrid systems offer volume reduction possibilities and the passive components, inductance, transformer and capacitor, represent a brake on this miniaturization. Inductive components such as coils or transformers are key elements of power electronics. These are well known and mastered components with regard to their discrete form, but their integration is still at the study stage and is still far from industrialization,  $[1-3]$  $[1-3]$  $[1-3]$ . In this work, we will focus on the design,

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manufacture and characterization of spiral planar coils on PCB-FR4 [[4\]](#page-14-2) it is a composite used in electronic printed circuit boards. It is composed of an epoxy resin matrix and loaded with 8 folds of glass fibers woven in 0°/90° directions. The design of a PCB substrate inductor is difficult to modify once built on the PCB. The advantage of this technology who using lithographic techniques and microvia technology is now able to produce devices with micron precision and almost as small a size [[5,](#page-14-3) [6\]](#page-14-4). We have targeted two types of coils:We have considered two types of inductors: standard and tapered inductors. The second type of inductor is characterised by an increasing track width according to the radius. This approach is of particular interest to the inductor as the total DC resistance will be effectively reduced to agiven number of turns. Indeed, on one hand, this will compensate for the variation of the resistance linked to the increase of the conductor width of the inductor and on the other hand, it will reduce the proximity effect and the capacitive effect between turn. The gain is less perceptible because we have considered the same occupied space to all prototypes of inductors studied. This study has targeted the following topologies: circular, square which are represented in Fig. [1.](#page-1-0) The parameters that have been taken into account in this study are the topology, the turns' width, the interturn distance and the thickness of the conductor. The production and the characterization took place in the Laboratory on Plasma and Conversion of EnergyUMR5213, Team MDCE, Toulouse, France [[7](#page-14-5)].



<span id="page-1-0"></span>**Fig. 1** Diferent forms of studied topologies [\[8](#page-14-7)]



<span id="page-1-1"></span>**Fig. 2** Diferent prototypes of integrated coils realized **a** square, **b** circular

# **2 Experimental**

# **2.1 Presentation of the Diferent Topologies of Planar Integrated Coils Studied**

The studied topologies are presented in Fig. [1](#page-1-0). These are the square and circular topologies.

## **2.2 Presentation of Realized Prototypes**

Figure [2](#page-1-1) presents the prototypes of planar integrated coils realized in this study.



<span id="page-1-2"></span>**Fig. 3** Geometrical parameters of a square-shaped PCB inductoride view of the PCB inductor



<span id="page-1-3"></span>**Fig. 4** Representation of diferent widths in inductance with variable width **a** and fxed width **b**

## **2.3 Planar Inductances's Characteristics**

In this section, we present the geometrical andelectrical characteristics of standard and tapered inductors [[1](#page-14-0), [9\]](#page-14-6) (Fig. [3\)](#page-1-2).

For a given form, an inductance is characterized, as shown in Fig. [4](#page-1-3), by the number of turns n, the width of the conductor w, the spacing between turns s, the thickness t of conductor, the conductor's total length lt, the average diameter, the diameters outside and inside dout and din. The dimensions of the different topologies are as follows:  $dout = 10$  mm,  $din = 1$  mm,  $n=3$  and  $t=35$  µm. For a three-turn variable-width coil, w1, w2 and w3 are the winding widths of each tower, as shown in Fig. [4.](#page-1-3)

# **2.4 Determination of Geometric Parameters**

## **2.4.1 Calculation of the Length**

The total length of the inductance is given by the following expression:

$$
l_t = nd_{avg} N \tan\left(\frac{\pi}{N}\right) \tag{1}
$$

For a square inductor,  $N = 4$ . N is a big number for the circular inductor, where we get the expressions of the total length lt, Eq. ([2](#page-2-0)).

$$
l_{t} = \frac{\pi}{2} \left[ 2n d_{in} + n(n+1)w + (n-1)ns \right]
$$
 (2)

with 
$$
d_{avg} = \frac{d_{out} + d_{in}}{2}
$$
 (3)

### **2.4.2 Calculation of the Spacing Between Turns s**

The following expression we have developed allows us to calculate the inter turns

$$
s = \frac{d_{out} - d_{in} - 2nw}{(n+1)}
$$
\n<sup>(4)</sup>

This expression is applicable for all cases. In the case of our coil:  $n = 3$  et  $d_{in} = 1$  mm et  $d_{out} = 10$  mm et w=0.9 mm,  $s = 0.54$  mm.

# **2.5 Integrated Planar Micro Inductance Manufacturing Process on PCB‑FR4**

[[11](#page-14-9)]

The fabrication process concerns different integrated inductance topologies on a substrate of PCB-FR4 [[1\]](#page-14-0) for diferent thicknesses (0.3 mm, 0.9 mm, 1.6 mm). The copper conductor is deposited on the substrate. [\[10,](#page-14-8) [11\]](#page-14-9). These prototypes were made at LAPLACE laboratory in Toulouse (LAPLACE) [[7](#page-14-5)].

#### <span id="page-2-0"></span>**2.5.1 Cuttingsteps of PCB parts**

We cut out  $1.5 \times 1.5$  cm<sup>2</sup> PCB-FR4 substrate parts for different thicknesses 0.3, 0.9, 1.6 mm, by the chainsaw shown in Fig. [5.](#page-2-1) This substrate is a support of insulating material intended for receive the impression of an electrical or electronic circuit and the various components of this circuit to form hybrid or monolithic circuits. \Copper windings of 35 μm thickness are then assembled on these substrates (PCB-FR4) (Figs. [6](#page-2-2), [7,](#page-3-0) [8](#page-3-1), [9,](#page-3-2) [10](#page-3-3), [11](#page-3-4), [12,](#page-4-0) [13](#page-4-1) and [14\)](#page-4-2).

<span id="page-2-2"></span>

**Fig. 6** Complete cutting equipment

<span id="page-2-1"></span>**Fig. 5** Manufacturing process Step2 : Enrésinement Step3: UV photolithography Step1: Metallization Step6: mold removal and Step5 : electrolytic deposit Step4 : Development engraving of the metal Copper resin Substrat Photo resistant Boot laver



**Fig. 7** Chainsaw (Secotom 10—STRUERS) with disc



**Fig. 10** System of chemical etching

<span id="page-3-0"></span>

**Fig. 8** PCB-FR4 substrate piece

<span id="page-3-1"></span>

**Fig. 9** Mask of the prototypes to be realized. **a** printed on paper, **b** printed on transparent paper **c** printing on glass plates

<span id="page-3-3"></span>

**Fig. 11** Realized prototypes at LAPLACE laboratory

# <span id="page-3-4"></span>**2.5.2 Realization of the Electric Circuit**

We first realized on the flex, the copper circuits of the coils of the diferent topologies. Before any process, it is necessary to clean the PCB plates.

# <span id="page-3-2"></span>**2.5.3 Preparation of the Engraving**

The mask is transferred to the copper-metallized PCB-FR4 using photolithography which aims to reproduce precise patterns on diferent layers, whether for engraving or deposition steps, the patterns of this mask will be transferred to a movie.

<span id="page-4-0"></span>





<span id="page-4-1"></span>**Fig. 13** Equivalent electrical circuit of a planar inductance



**Fig. 14** Simplifed circuit on the bench

# <span id="page-4-2"></span>**2.5.4 Lamination and Photolithography of the Photosensitive Dry Film**

We have printed the schematics of the diferent topologies of the integrated inductors on a glass plate covered with a layer of chromium in order to obtain the mask.

#### **2.5.5 Engraving**

After etching the metallized inorganic substrate and masked with iron perchloride, we removed the photosensitive flm and we etched the bonding layer, that is to say eliminated copper from the surface of the fex by wet etching which allows to remove the copper on the surface of the fex. This operation consists in soaking the sample in a solution composed of iron perchloride and the water which is heated to about 27 °C. The solution preserves the copper by dissolving the part of the unprotected copper with the cured flm and reveals the desired pattern.

## **2.5.6 Rinsing**

With water of the fnal component in a solvent which is acetone or NaOH to remove the blue flm and reveal the conductive lines.

## **2.5.7 Oven Passage**

Pass the component in the oven at 70 °C to avoid oxidation.

## **2.5.8 Varnishing**

The inductances realized are possibly varnished to prevent oxidation of the conductive copper.

## **2.5.9 The Deposit**

Bonding is essential to ensure the interconnection of the central stud to the external stud.

Topology	All inductors		variable width	Fixed width
	$l_{\rm t}$ (cm)	$t \text{ (um)}$	$w1/w2/w3$ (mm)	$W$ (mm)
Circular	4.7	35	0.3/0.6/0.9	0.9
Square	6.0	35	0.3/0.6/0.9	0.9

<span id="page-5-0"></span>**Table 1** Geometric parameters of inductances with fxed and variable widths

<span id="page-5-2"></span>**Table 3** Square coil with variable width



<span id="page-5-1"></span>**Table 2** Square coil with fxed width

Thickness (mm)	$\text{Rs (m}\Omega$	$Cs$ ( $pF$ )	$\mathbf{L}\mathbf{s}$ (nH)	Ls/Rs ( $H/m\Omega$ )	
0.3	41.60	658.55	55.88	1.415	
0.9	69.68	270.00	55.54	0.97	
1.6	72.69	253.58	22.83	3.183	

<span id="page-5-3"></span>**Table 4** Circular coil with fxed width

Thickness (mm)	$\text{Rs (m}\Omega$	$Cs$ (pF)	$\mathbf{L}\mathbf{s}$ (nH)	Ls/Rs ( $H/m\Omega$ )
0.3	32.63	600.81	39.78	1.219
0.9	40.63	420.00	35.50	0.916
1.6	45.51	374.00	29.89	1.522

<span id="page-5-4"></span>**Table 5** Circular coil with variable width

# Thickness (mm) Rs (m $\Omega$ ) Cs (pF) Ls (nH) Ls/Rs (H/m $\Omega$ ) 0.3 55.02 416.6 53.86 0.978 0.9 67.51 303.1 49.59 0.730 1.6 70.27 692.0 36.76 0.525

## **2.5.10 Realized Prototypes**

Below, the realized prototypes at LAPLACE laboratory.

## **2.6 Characterization**

The characterization of the realized prototypes requires, on the one hand, suitable measurement means and on the other hand, a model making it possible to take into account the main physical phenomena.

#### **2.6.1 Description of the Measuring Bench**

We used the measuring bench which is composed of a LCR meter HP (Agilent 4194A) which performs the vector measurement of current–voltage, and module and phase of impedance.

#### **2.6.2 Choice of Equivalent Circuit Model**

The model includes the series inductance  $L<sub>s</sub>$ , the series resistor  $R_s$ , the coupling capacitance between the turns  $C_s$ , the capacitance associated with the substrate of PCB, the capacity of substrate.

#### **2.6.3 Simplifedphysical Model of an Inductor on PCB‑FR4**

Figure [13](#page-4-1) shows the equivalent scheme in  $\pi$  of a planar spiral coil [[9,](#page-14-6) [12\]](#page-14-10).

<span id="page-5-5"></span>**Table 6** Geometric parameters used for simulation



We have chosen the RLC equivalent model that supports inductance capacity and substrate resistance to measure parameters as a function of frequency [[6](#page-14-4)] (Table [1\)](#page-5-0).

# **3 Results and Discussions**

# **3.1 Measurement Results**

The tables below present the measurement results of the Rs, Ls, Cs parameters of the diferent planar inductances. Note from Tables [2,](#page-5-1) [3](#page-5-2), [4](#page-5-3) and [5](#page-5-4) that the values of the series



<span id="page-6-0"></span>**Fig. 15** Serial inductance according frequency variation case of square inductance with fxed width



<span id="page-6-1"></span>**Fig. 16** Serial inductance according frequency variation case of square inductance with variable width

resistance increase from the smallest value, which varies from 0.3 to 1.6 mm, while the series capacitance and the series inductance decrease as the thickness increases  $(Table 6)$  $(Table 6)$ .

# **3.2 Infuences of Electrical Parameters on the Behavior of Micro‑Coils**

The results of measurements obtained with the RLC meter concern  $|z|$ , f and  $\varphi$  respectively the Z modulus, the frequency and the phase shift, for the diferent topologies of the micro inductances. The expressions below have allowed us to draw diferent curves presented in this section.

$$
Z = r + jLw = |Z|e^{i\varphi} \quad \text{avec} \quad \omega = 2\pi f \tag{5}
$$



Inductance Ls (nH)

<span id="page-6-2"></span>**Fig. 17** Serial inductance according frequency variation case of circular inductance with fxed width

Frequency(Hz)



<span id="page-6-3"></span>**Fig. 18** Serial inductance according frequency variation case of circular inductance with variable width

$$
|Z| = \sqrt{r^2 + (L\omega)^2}
$$
\n<sup>(6)</sup>

$$
R_s = \frac{|Z|}{\sqrt{1 + \tan^2 \varphi}}\tag{7}
$$

$$
\tan \varphi = \frac{L\omega}{r} \tag{8}
$$

*<sup>𝜑</sup>*: déphasage de Z, |*Z*|: module de*Z, L*: Inductance

#### **3.2.1 Inductance as a Function of Frequency**

Figures [15,](#page-6-0) [16,](#page-6-1) [17](#page-6-2) and [18](#page-6-3) show the variation of the series inductance as a function of the frequency for all the diferent



<span id="page-7-0"></span>**Fig. 19** Phase variation according frequency for square inductance with fxed width



<span id="page-7-1"></span>**Fig. 20** Phase variation acoording frequency for square inductance with variable width

realize integrated coils (fxed and variable widths). The evolution of the inductance is explained by the fact that the thickness of skin in a conductor strongly depends on the frequency. The decrease of this thickness increases the ohmic resistance of the conductor and amplifes the losses by Joule efect. The increase of the resistance decreases the value of the current and consequently the value of the inductance of the micro-coils, these results are in agreement with that found in the literature [\[13](#page-14-11), [14](#page-14-12)].

### <span id="page-7-4"></span>**3.2.2 The Phase as a Function of Frequency**

The Figs. [19](#page-7-0), [20,](#page-7-1) [21](#page-7-2) and [22](#page-7-3) indicate the variation of the phase as a function of the frequency, in the case of a planar circular coil with a fxed and variable width, respectively.



<span id="page-7-2"></span>**Fig. 21** Phase variation according frequency for circular inductance with fxed width



<span id="page-7-3"></span>**Fig. 22** Phase shift variation according frequency for circular inductance with variable width

It can be seen from these curves that the coils realizes and have a resistive and then inductive behavior. This means that the prototypes manufactured are purely inductive. This reasoning is valid for all the reels made. We also notice that the thickness infuences the phase shift.

#### <span id="page-7-5"></span>**3.2.3 Resistance as a Function of Frequency**

Figures [23,](#page-8-0) [24,](#page-8-1) [25](#page-8-2) and [26](#page-8-3) show the variation of the series resistance as a function of the frequency for the various integrated coils made (fxed and variable widths). We notice that resistance grows lo with frequency. Indeed, the increase of the frequency causes the decrease of the thickness of skin, which makes the area of the conductor where circulates the



<span id="page-8-0"></span>**Fig. 23** Variation in series resistance depending on the frequency case of square inductance with fxed width



<span id="page-8-1"></span>**Fig. 24** Variation in series resistance depending on the frequencycase of square inductance with variable width

current of increasingly weak. The decrease of this thickness increases the ohmic resistance of the conductor and amplifes the losses by Joule efect.

Figures [27](#page-9-0), [28](#page-9-1) and [29](#page-9-2) illustrate the evaluation of impedance versus frequency of standard and tapered inductors. We note that impedance is more important in the case of the tapered inductor. Higher impedance implies smaller current and hence smaller parasitic efects of the series capacitance and proximity effect. This is why a inductance with variable conductor presents, a the best behavior (Fig. [30\)](#page-9-3).

#### **3.2.4 Factor of Quality in Function of the Frequency**

Figures [31,](#page-10-0) [32](#page-10-1), [33](#page-10-2) and [34](#page-10-3) show the variation of quality factor versus frequency for square and circular fxed and



<span id="page-8-2"></span>**Fig. 25** Variation in series resistance depending on thefrequency case of circular inductance with fxed width



<span id="page-8-3"></span>**Fig. 26** Variation in series resistance depending on the frequency case of circular inductance with variable width

variable width inductors. We note that the quality factor increases until it reaches a maximum 25 value at the frequency of use of the component and then decreases beyond this value. This fgure also shows that the variable width coil has the largest quality factor value for the three values of the substrate. This is because of the following reasons: the series resistance, the series capacitance, the oxide capacity and the capacitance of the substrate are less important in the case of a variable-width inductor. The variable-width coils have a higher quality factor than the standard coils which are the seat of greater parasitic efects, these results are in agreement with that found in the literature [[15\]](#page-14-13).



<span id="page-9-0"></span>**Fig. 27** Variation in the impedance depending on the frequencycase of square inductance with fxed width



<span id="page-9-1"></span>**Fig. 28** Variation in the impedance depending on the frequencycase of square inductance with variable width

## **3.2.5 Validation of our Results**

Figure [35a](#page-11-0), b respectively show the impedance and the phase shift as a function of the frequency  $[16]$  $[16]$ . We find that both gaits are identical to those we obtained, see Sects. [3.2.2](#page-7-4) (Figs. [19](#page-7-0)[–22\)](#page-7-3) and [3.2.3](#page-7-5) (Figs. [27–](#page-9-0)[30\)](#page-9-3). This comparison allows us to conclude that the sizing procedure and the implementation protocol are correct. This validates all our work (Fig. [36\)](#page-11-1).

# **3.3 Electromagnetic Behavior of Prototypes Integrated Coils**

The purpose of these simulations is to determine for both types of coils of diferent topologies which of those it has



<span id="page-9-2"></span>**Fig. 29** Variation in the impedance depending on the frequenc case of circular inductance with fxed width



<span id="page-9-3"></span>**Fig. 30** Variation in the impedance depending on the frequency, case of circulare inductance with variable width

an optimal distribution of current and electrical potential in the conductor and therefore it has a good distribution of the feld lines. The results obtained will help us decide which topology to choose. These simulations were performed for the following frequencies: 100 Hz, 6.3246  $10^4$  Hz et 4.10<sup>7</sup> Hz.

#### **3.3.1 Prototyping Process**

Prototyping the retained coils requires several steps: Constructing the prototype geometry, defning the materials and generating the mesh. [[17,](#page-14-15) [18\]](#page-14-16). material associated with each object of the geometry is identifed by its physical properties. In our case, it is the copper for the turns, because we were interested mainly in the phenomena that



<span id="page-10-0"></span>**Fig. 31** Quality factor according to the frequency for fxed width square inductance



<span id="page-10-1"></span>**Fig. 32** Quality factor according to the frequency for variable width square inductance

take place in the conductive ribbon with the following physical properties:  $\epsilon r = 1$ ,  $\mu r = 1$  and  $\rho = 1.68.1020 \mu \Omega$ . cm. The generation of the mesh consists of cutting the geometric model into triangles. The resolution process gives solutions to the operating frequency chosen. Figure [34a](#page-10-3) and b show the mesh of the conductors of the square and circular coils [[19](#page-14-17)].

**3.3.1.1 Current Density Distribution** The 3D simulation results, obtained by solving the Maxwell equations by the fnite element method [[21](#page-14-18)], presented in this section, allow to visualize the distribution of the density of the electric current in the diferent topologies of coils.



<span id="page-10-2"></span>**Fig. 33** Quality factor according to the frequency for fxed width circular inductance



<span id="page-10-3"></span>**Fig. 34** Quality factor according to the frequency for variable width circular inductance

• Case of fixed width coils

Figure [37a](#page-12-0)–c show the distribution of the current density in different fixed width coil topologies for  $w = 0.9$  mm and for diferent operating frequency values. We notice that this density is minimum at the exit of the coil because of the value of the resistance of the conductor.

• Case of variable width coils



<span id="page-11-0"></span>**Fig. 35** Variation in **a** the impedance depending on the frequency **b** phase shift variation versus frequency [[16](#page-14-14)]

Figure [38](#page-12-1)a–c show that the circular topology shows a better distribution of the current density, hence a smaller resistance. This confrms its better quality factor compared to the square topology. In deed, unlike the circular topology, the current density is not uniform in the square spirals, it is more important at the angles that induce inhomogeneous resistances in the conductors [[3](#page-14-1)]. We note, that the efect of skin and proximity are present and manifest especially between adjacent turns as shown in these fgures.

## **3.4 Examples of Applications**

We realized three applications containing the prototypes of micro inductances realized. The frst application, Fig. [39a](#page-13-0) is a passive audio flter. It contains a circular micro inductance fixed width and thickness of FR4 PCB  $e = 0.3$  mm. The second application is an active and passive/active audio flter. It contains a fxed width rectangular micro inductor with a thickness of FR4 PCB  $e=0.9$  mm, see Fig. [39b](#page-13-0). The third application is a planar-type DC buck converter DC/DC converter which contains a flter with planar inductance, see Fig. [40c](#page-13-1).



<span id="page-11-1"></span>**Fig. 36** Mesh of planar inductor (square and circular) [[20](#page-14-19)]

#### **3.4.1 Pictures of the Diferent Examples of Applications**

Below, the images of the diferent applications.

# **4 Conclusion**

The work presented in this paper concerns the realization of flters containing planar type inductors with fxed and variable width conductors. The geometric and electrical dimensioning of these inductors is an important step that requires taking into account many electrical and geometrical parameters. The variable width coil increases the value of the inductance. It maintains the same inductance value while reducing the proximity effect and parasitic effects of the series capacitance. The conductive spirals of all the







<span id="page-12-0"></span>**Fig. 37** Distribution of magnetic fux density and electrical potential in square standard coils for  $w=0.9$  mm. **a**  $f=100$  Hz, **b**  $f=6.3246$ 104 Hz, **c** f=4107 Hz







 $(b)$ 



<span id="page-12-1"></span>**Fig. 38** Distribution of the density of the magnetic fux and the electric potential in the circular standard coil for w=0.9 mm. **a** f=100 Hz, **b** f=6.3246104 Hz, **c** f=4.107 Hz

 $\bullet$ 

 $4.5$ 

 $3.5$ 

 $\mathbf{a}$ 

 $2.5$ 

 $1.5$ 

 $\overline{2}$ 

 $\mathbf{1}$ 

 $0.5$ 

ö

 $3.5$ 

 $2.5$ 

 $1.5$ 

 $0.5$ 

 $\overline{\mathbf{z}}$ 

 $\overline{2}$ 

 $0.25$ 

 $0.2$ 

0.15

 $0.1$ 

0.05





<span id="page-13-0"></span>**Fig. 39** Exempels of applications **a** Passif PlanarFilter **b** Passif/Actif Planar Filter

prototypes were made on the FR4 PCB whose low cost use makes it possible to respond to a very large number of applications, ranging from a few tens of kHz to several hundred MHz. The obtained results show that inductance decreases with frequency, this applies to all inductors. They also show that the two types of inductors, fxed and variable width, made on the FR4 PCB have the same electrical characteristics while occupying the same area. The maximum value of inductance is obtained with a square topology and the minimum value with a circular topology. This is due to the geometrical specifcations of each topology. The electrical resistance of the square inductor is greater than that of the circular inductance for the fxed and variable width coils. Indeed, the total length of the conductor of the square inductor is greater than that of the conductor of the circular inductor. Since the impedance is greater in the case of a variable-width inductor, a low-value current fows, which implies a decrease in parasitic effects of the series capacitance and the proximity efect. The manufacture of these inductors was carried out at the Laplace laboratory in Toulouse, France.



 $(a)$ 



<span id="page-13-1"></span>

**Fig. 40** Pictures of the diferent examples of applications **a** secondorder passive audio flter of the second order, **b** second order passive/ active planar audio flter, **c** and **d** buck converter DC/DC powered by a solar cell and controlled by an arduino uno board

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